



FeNiCo29/18-COPPER-FeNiCo29/18 CLAD
FOR PCB
AND MUCH MORE



**Auerhammer
Metallwerk**
Wickeder Group

www.auerhammer.com



To ensure optimal performance and reliability, sensitive electronics must be protected.

FeNiCo29/18-COPPER-FeNiCo29/18 clad is developed to meet your demands for very low thermal resistance for tabs in ceramic-metal packages for semiconductor devices and other PCB elements.

Advantages:

- › Fighting thermal expansion coefficient and connecting similar material together
- › Adjusted thermal coefficient
- › Thermal management



Configure your Cladding strip online:
www.clad-configurator.de

PORTFOLIO WICKEDER GROUP

- › Clad Materials › Bimetals › Nickel Strips › Metal Foils
- › Photochemical Etching › Sheet Metal Working › Waterjet Cutting
- › Electroforming › Parylene Coating › Materials Engineering etc.



CONTACT